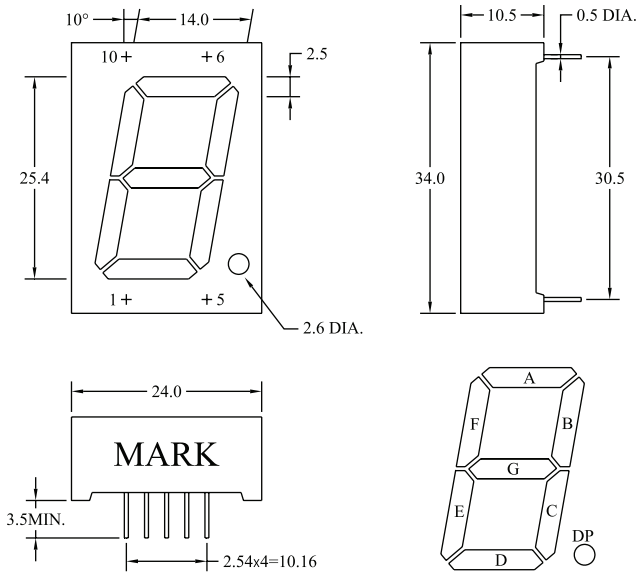
1" Single Digit Display

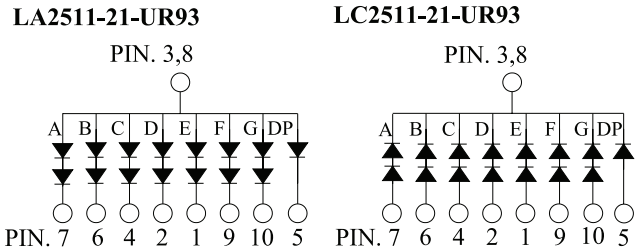
RoHS Compliant

Package Dimensions:



All dimensions are in mm
Tolerance: ±0.25mm
The slope angle of any PIN may be ±5° max

Internal Circuit Diagram:



Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol		Rating	Unit
Power Dissipation - Pre Segment	P_D	DP	72	mW
		Seg	144	
Pulse Current (1/10 Duty Cycle, 0.1ms Pulse Width)	I_{FP}		100	mA
Forward Current - Per Chip	I_F		30	mA
Reverse (Leakage) Current - Per Chip	Ir		100	µA
Reverse Voltage - Per Chip	V_R		5	V
Operating Temperature Range	Topr.		-25 to +85	°C
Storage Temperature Range	Tstg.		-40 to +100	°C
Soldering Temperature	Tsol.		Dip Soldering: 260°C for 5sec. Hand Soldering: 350°C for 3 sec.	

Electrical & Optical Characteristics:

Parameter	Symbol		Condition	Min.	Typ.	Max.	Unit
Luminous Intensity - Per Segment	Iv		If=10mA	15.4	34		mcd
Forward Voltage	Vf	DP	If=20mA		1.9	2.4	V
		Seg	If=20mA		3.8	4.8	
Peak Wavelength	λp		If=20mA		650		nm
Dominant Wavelength	λd		If=20mA		639		nm
Reverse Current - Per Chip (Leakage Current - Per Chip)	Ir		Vr=5V			100	μA
Spectrum Line Halfwidth	Δλ		If=20mA		20		deg
Response Time	T				250		nm

Note: Customer's special requirements are also welcome.

Electrical & Optical Characteristics: Hyper Red

Bin Name		R	S	T	U	V
IV (mcd)	Min.	15.4	22	31.45	44.95	58.45
	Max.	22	31.45	44.95	58.45	76

Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)

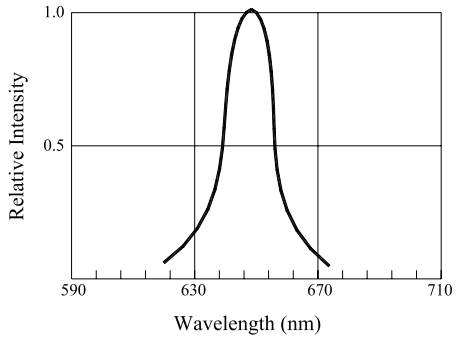


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

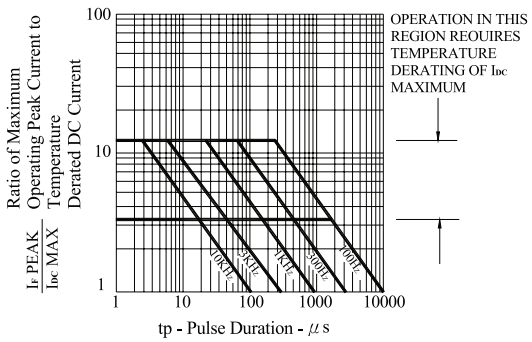


Fig.2 MAXIMUM TOLERABLE PEAK CURRENT VS. PULSE DURATION

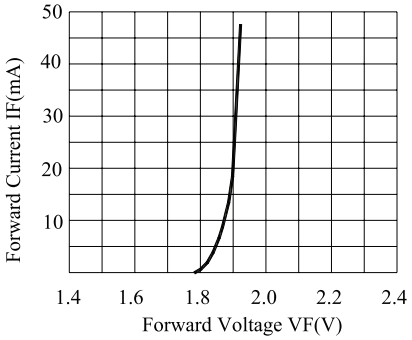


Fig .3 FORWARD CURRENT VS. FORWARD VOLTAGE PER CHIP

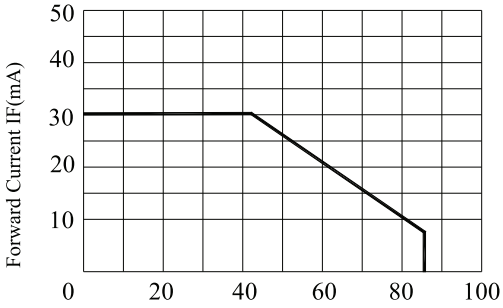


Fig.4 FORWARD CURRENT VS. DERATING CURVE

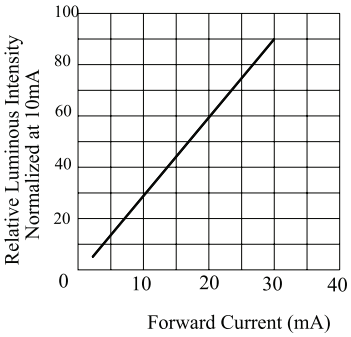


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

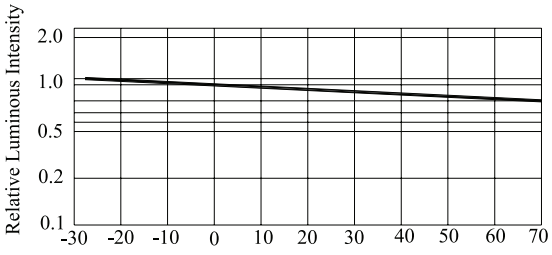


Fig.6 LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

Part Number Table

LED Chip		Face Colour		Part Number
Material	Emitting Colour	Surface	Segments	
AlGaIn / GaAs	Deep Red	Grey	White	703-0176
AlGaIn / GaAs	Deep Red	Grey	White	703-0177